



Docket No.: 042390.P7045D

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Ramalingam, et al.

Application No.: 09/874,666

Filed: June 5, 2001

For: A Controlled Collapse Chip
Connection (C4) Integrated Circuit
Package Which Has Two Dissimilar
Underfill Materials

Examiner: David E. Graybill

Art Group: 2827

SUPPLEMENTAL AMENDMENT AND RESPONSE

BOX NON-FEE AMENDMENT
Assistant Commissioner for Patents
Washington, DC 20231-9998

Sir:

In response to the outstanding Office Action, mailed June 18, 2003, Applicants respectfully amend the above-identified Application as follows:

IN THE CLAIMS

Following is a complete set of claims as amended with this Response. This complete set of claims includes claims 7 and 13, cancelled claim 26-30 and new claims 31-35.

1 1-6. (Cancelled.)

1 7. (Currently Amended) A process for underfilling an integrated circuit that is

2 mounted to a substrate, comprising: